

Features

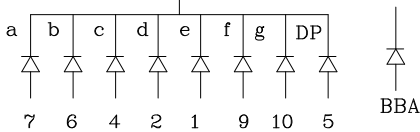
- 0.56 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE : 400PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

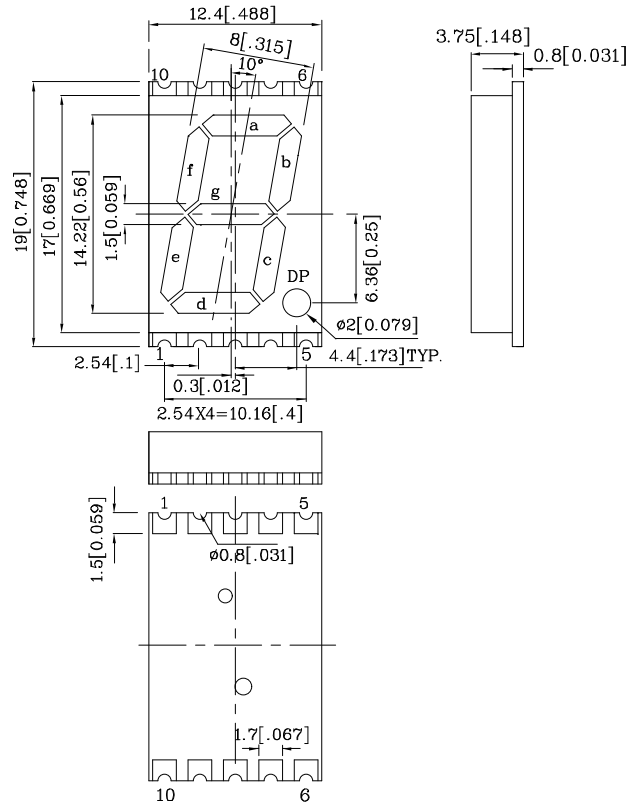


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Notes:

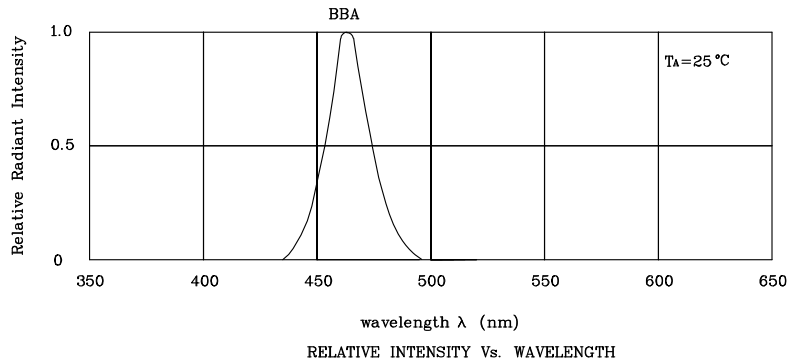
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.
4. The gap between the reflector and PCB shall not exceed 0.25mm.



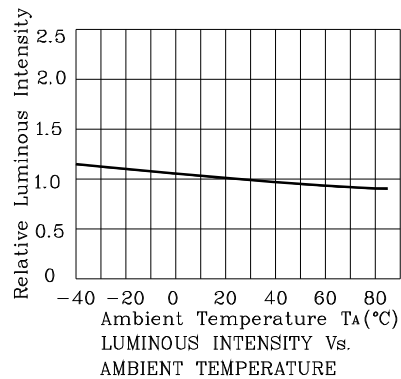
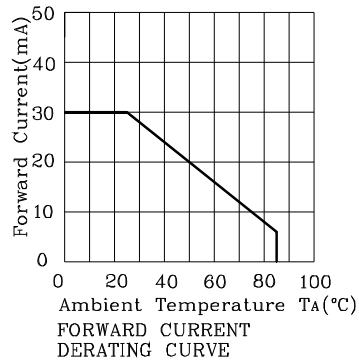
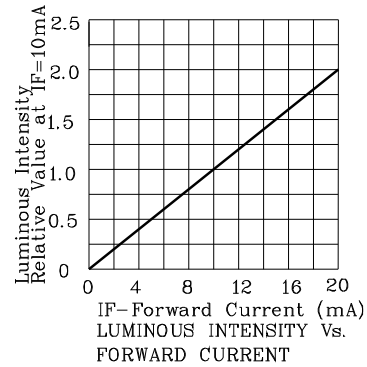
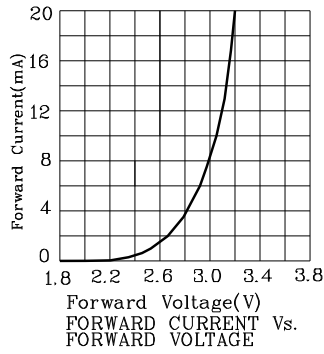
Absolute Maximum Ratings (TA=25°C)		BBA (InGaN)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	100	mA
Power Dissipation	PT	120	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V

Operating Characteristics (TA=25°C)		BBA (InGaN)	Unit
Forward Voltage (Typ.) (IF=10mA)	VF	3.05	V
Forward Voltage (Max.) (IF=10mA)	VF	4.0	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=10mA)	λ P	468	nm
Wavelength of Dominant Emission (Typ.) (IF=10mA)	λ D	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=10mA)	Δλ	21	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	100	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd		Wavelength nm λ P	Description
			min.	typ.		
XZFBBA14C	Blue	InGaN	1900	8990	468	Common Cathode. Rt. Hand Decimal



❖ BBA



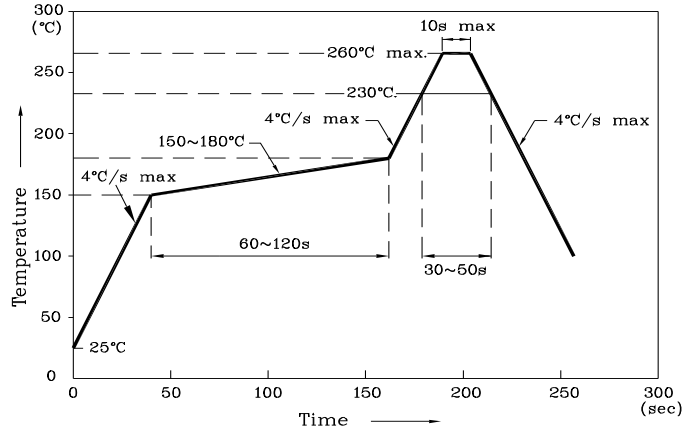
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

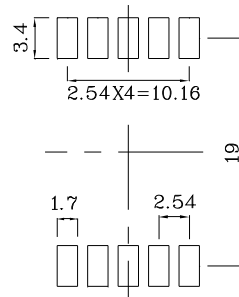
Reflow Soldering Profile For Lead-free SMT Process.



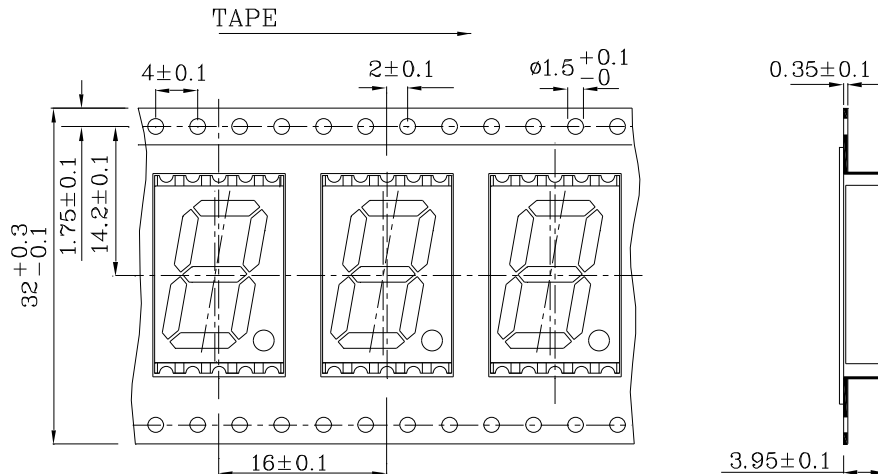
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance:± 0.15)

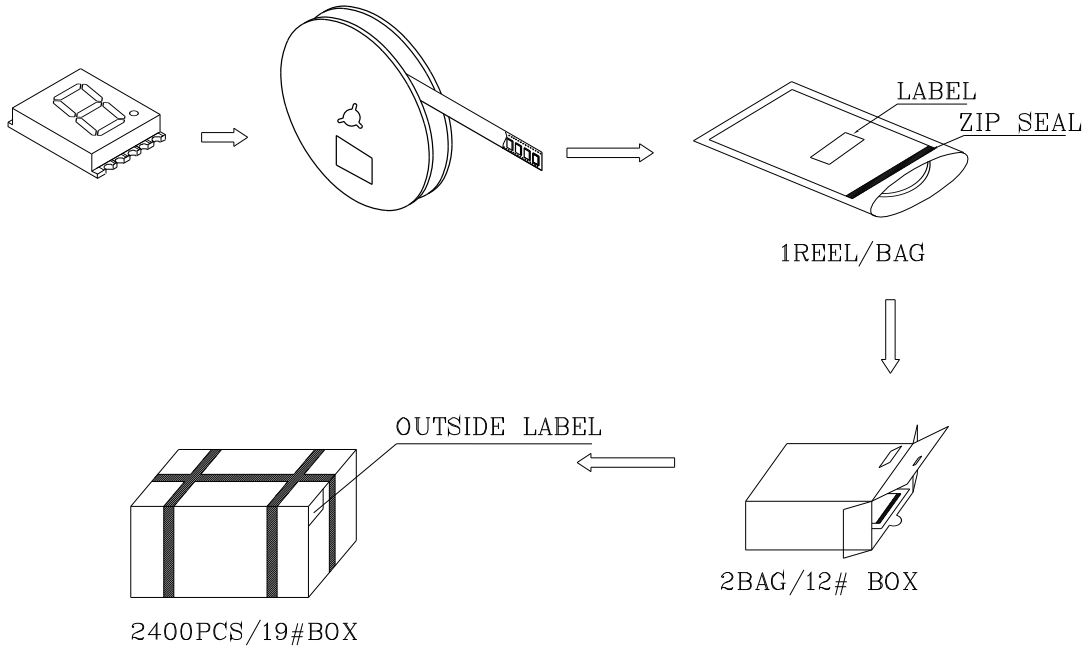


❖ Tape Specification (Units : mm)



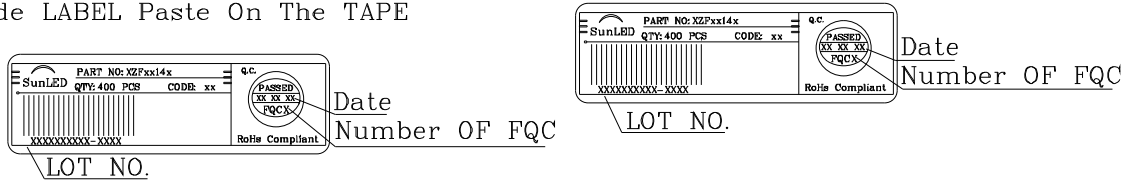
PACKING & LABEL SPECIFICATIONS

XZFBBA14C



Outside LABEL Paste On The BAG

Inside LABEL Paste On The TAPE



Outside LABEL Paste On The 19#Box

Outside LABEL Paste On The 12#Box

